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(71) Applicant (for all designated States except US): **KLA-TENCOR CORPORATION** [US/US]; 1 Technology Drive, Milpitas, California 95035 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **MAISON, Benoit** [BE/BE]; Rue du Sol 1, B-1301 Wavre (BE). **HILL, Andy** [US/US]; 1382 Hillcrest Court, San Jose, California 95120 (US). **HERMANS, Laurent** [BE/BE]; De Villegasplein 2, B-2150 Borsbeek (BE). **NIJS, Frans** [BE/BE]; Nieuwstraat 48, B-3971 Leopoldsburg (BE). **VAN GILS, Karel** [NL/BE]; Anemonenlaan 12, B-3052 Blanden (BE). **WOUTERS, Christophe** [BE/BE]; Krommepad 46, B-2490 Balen (BE).

(74) Agent: **REICHERT, Werner F.**; Bismarckplatz 8, 93047 Regensburg (DE).

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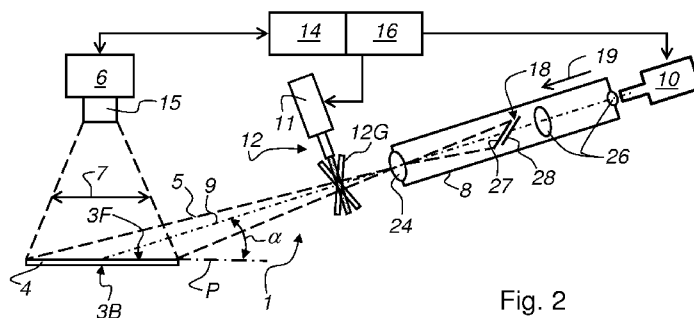


Fig. 2

(57) Abstract: An apparatus (1) and a method for the three dimensional inspection of saw marks (2) on at least one surface (3) of a wafer (4) are disclosed. At least one camera (6) is required to capture an image of the entire surface (3) of the wafer (4). At least one line projector (8) provides a light bundle (5), centered about a central beam axis (9). The line projector (8) is arranged such that the central beam axis (9) is at an acute angle (α) with regard to the plane (P) of the wafer (4). A line shifter (12) is positioned in the light bundle (5) between each line projector (8) and the surface (3) of the wafer (4). A frame grabber (14) and an image processor (16) are used to synchronize and coordinate the image capture and the position of the pattern (20) of lines (22) on the front side (3F) and/or the back side (3B) of the wafer (4).